# HS3ABH – HS3MBH Taiwan Semiconductor

3A, 50V - 1000V High Efficient Surface Mount Rectifier

### FEATURES

- AEC-Q101 qualified
- Low power loss, high efficiency
- Low forward voltage drop
- Low profile package
- Fast switching for high efficiency
- Ideal for automated placement
- Glass passivated chip junction
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

### **MECHANICAL DATA**

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.093g (approximately)

		HS	HS	HS	HS	HS	HS	HS	HS	
PARAMETER	SYMBOL	3 <b>AB</b>	3 <b>BB</b>	3DB	3FB	3GB	3JB	ЗКВ	ЗМВ	UNIT
		н	Н	Н	н	Н	Н	н	н	
Marking and an the davias		HS	HS	HS	HS	HS	HS	HS	HS	
Marking code on the device		3AB	3BB	3DB	3FB	3GB	3JB	3KB	3MB	
Repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	300	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	210	280	420	560	700	V
Forward current	I <sub>F</sub>				ć	3				Α
Surge peak forward current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>				1(	00				A
Junction temperature	TJ				- 55 to	+150				°C
Storage temperature	T <sub>STG</sub>				- 55 to	o +150				°C

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	3	А		
V <sub>RRM</sub>	50 - 1000	V		
I <sub>FSM</sub>	100	А		
T <sub>J MAX</sub>	150	°C		
Package	DO-214AA (	SMB)		
Configuration	Single d	ie		







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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	60	°C/W

ELECTRICAL SPECIFIC		= 25°C unless otherwi	ise noted)			
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
(1)	HS3ABH HS3BBH HS3DBH HS3FBH	I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.0	V V V V
Forward voltage <sup>(1)</sup>	HS3GBH			-	1.3	V
	HS3JBH HS3KBH HS3MBH			-	1.7	V V V
Deverse every $(2)$		$T_J = 25^{\circ}C$	- I <sub>R</sub>	-	10	μA
Reverse current @ rated $V_R^{(2)}$		$T_J = 100^{\circ}C$		-	250	μA
Junction capacitance	HS3ABH HS3BBH HS3DBH HS3FBH HS3GBH HS3JBH HS3KBH	1MHz, V <sub>R</sub> = 4.0V	Сյ	80	-	pF pF pF pF pF pF
Reverse recovery time	HS3MBH HS3ABH HS3BBH HS3BBH HS3FBH HS3GBH	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>rr</sub> = 0.25A	t <sub>rr</sub>	-	50	pF ns ns ns ns ns ns
	HS3JBH HS3KBH HS3MBH			-	75	ns ns

#### Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
HS3xBH	DO-214AA (SMB)	3,000 / Tape & Reel

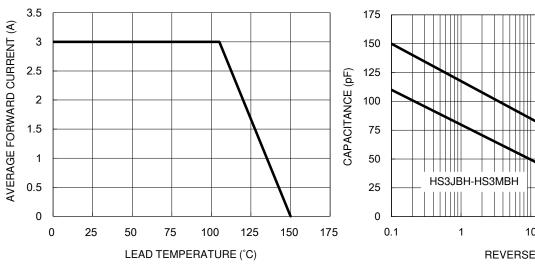
#### Notes:

1. "x" defines voltage from 50V(HS3ABH) to 1000V(HS3MBH)

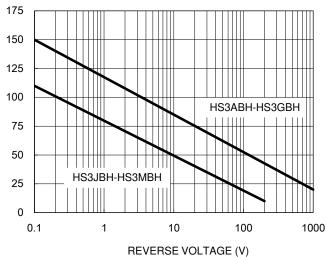


### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 



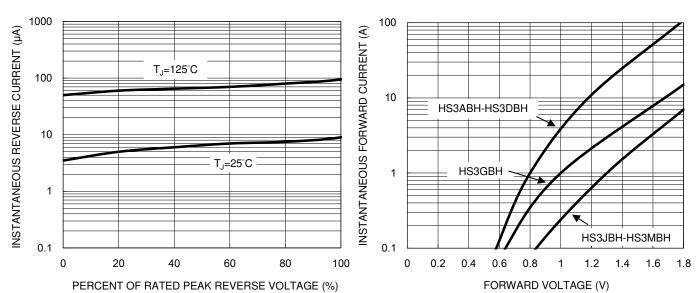
#### Fig.1 Forward Current Derating Curve



#### **Fig.2 Typical Junction Capacitance**

**Fig.3 Typical Reverse Characteristics** 

**Fig.4 Typical Forward Characteristics** 

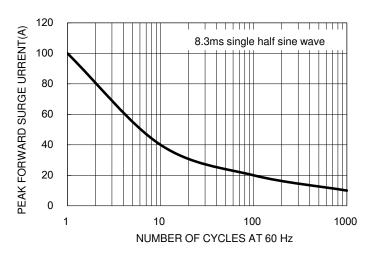




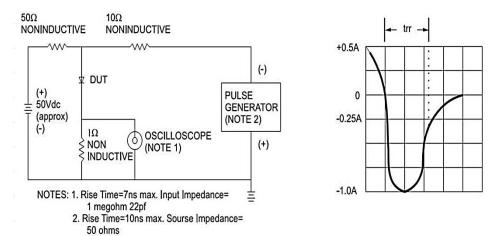
### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

#### Fig.5 Maximum Non-repetitive Forward Surge Current



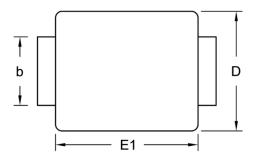
#### Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

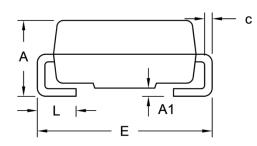




# PACKAGE OUTLINE DIMENSIONS

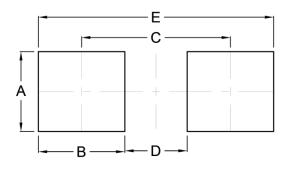
DO-214AA (SMB)





DIM. Uni		(mm)	Unit	(inch)
	Min.	Max.	Min.	Max.
A	1.95	2.65	0.077	0.104
A1	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
с	0.15	0.31	0.006	0.012
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.60	0.030	0.063

### SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.30	0.091
В	2.50	0.098
С	4.30	0.169
D	1.80	0.071
E	6.80	0.268

### **MARKING DIAGRAM**



P/N	= Marking Code
G	= Green Compound

YW = Date Code

F = Factory Code



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